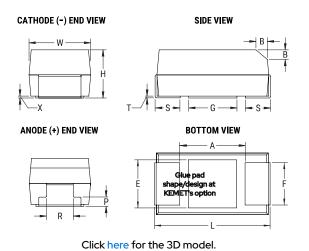


T493B155K035AH6120

T493 HRA, Tantalum, MnO2 Tantalum, HRA, 1.5 uF, 10%, 35 VDC, SMD, MnO2, Molded, High Reliability, N/A, 3 Ohms, 3528, 2.1 mm, 0.8 mm





General Information		
Series	T493 HRA	
Dielectric	MnO2 Tantalum	
Style	SMD Chip	
Description	SMD, MnO2, Molded, High Reliability	
Features	High Reliability	
RoHS	No	
Prop 65	WARNING: Cancer and reproductive harm - https://www.p65warnings.ca.gov /	
SCIP Number	1dd2e1b8-26dd-4d52-927c-6f9 d519011aa	
Termination	Tin Lead (SnPb)	
AEC-Q200	No	
Typical Component Weight	102.3 mg	
Notes	P and R dimensions represents the minimum solderable area of the termination surface entirely below cutout (if one is present).	

1.5 uF

Dimensions		
L	3.5mm +/-0.2mm	
W	2.8mm +/-0.2mm	
Н	1.9mm +/-0.2mm	
T	0.13mm REF	
S	0.8mm +/-0.3mm	
F	2.2mm +/-0.1mm	
A	1.9mm MIN	
В	0.4mm +/-0.15mm	
E	2.2mm REF	
G	1.8mm REF	
Р	0.35mm MIN	
R	1mm REF	
X	0.1mm +/-0.1mm REF	

T&R, 178mm

2000

Packaging Specifications

Packaging Quantity

Packaging

3mm +/-0.2mm	Tolerance	10%	
mm +/-0.2mm	Voltage DC	35 VDC (85C), 23.45 VDC (125C)	
I3mm REF	Temperature Range	-55/+125°C	
8mm +/-0.3mm	,	,	
2mm +/-0.1mm	Rated Temperature	85°C	
mm MIN	Dissipation Factor	6% 120Hz 25C	
	Failure Rate	N/A	
4mm +/-0.15mm	ESR	3 Ohms (100kHz 25C)	
2mm REF	Ripple Current	158 mA (rms, 100kHz 25C)	
8mm REF	• •	0.5 uA (5min 25°C)	
35mm MIN	Leakage Current		
nm REF	Testing and Reliability	Standard Testing Only	
lmm +/-0.1mm REF			

Specifications
Capacitance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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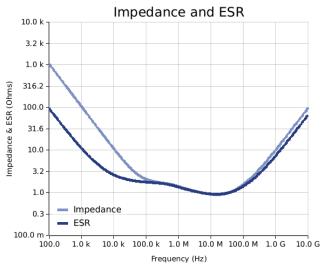


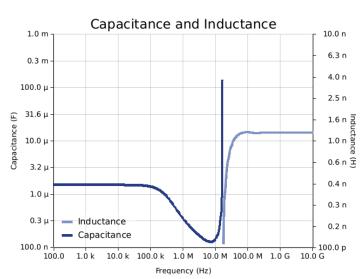


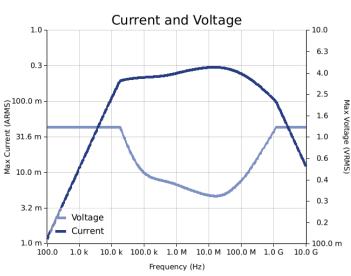
T493 HRA, Tantalum, MnO2 Tantalum, HRA, 1.5 uF, 10%, 35 VDC, SMD, MnO2, Molded, High Reliability, N/A, 3 Ohms, 3528, 2.1 mm, 0.8 mm

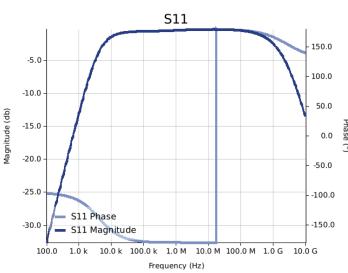
Simulations

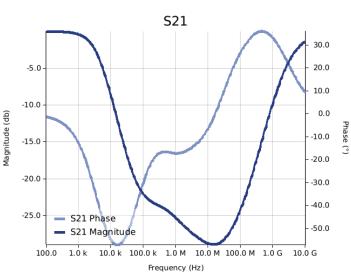
For the complete simulation environment please visit K-SIM.











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T493B155K035AH6120

T493 HRA, Tantalum, MnO2 Tantalum, HRA, 1.5 uF, 10%, 35 VDC, SMD, MnO2, Molded, High Reliability, N/A, 3 Ohms, 3528, 2.1 mm, 0.8 mm

These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for ripple Ripple Currenty votage vs. rrequency plots is unleast at an interact temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.

 Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

If you have any questions please contact K-SIM.

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